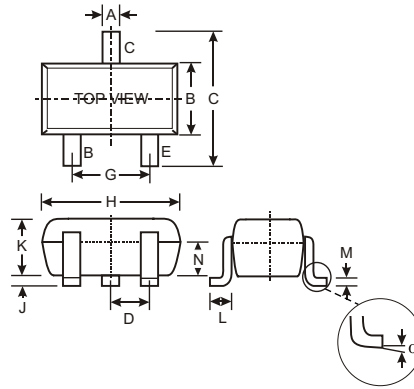


Features

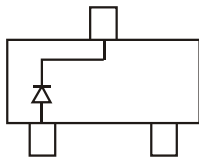
- Low Forward Voltage Drop
- Guard Ring Die Construction for Transient Protection
- Ideal for low logic level applications
- Low Capacitance
- Also Available in Lead Free Version

Mechanical Data

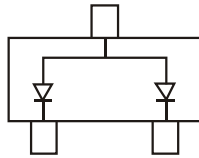
- Case: SOT-523, Molded Plastic
- Case Material UL Flammability Rating: 94V-0
- Moisture sensitivity: Level 1 per J-STD-020A
- Terminals: Solderable per MIL-STD-202, Method 208
- Also Available in Lead Free Plating (Matte Tin Finish). Please see Ordering Information, Note 4, on Page 3
- Polarity: See Diagrams Below
- Marking: See Diagrams Below & Page 3
- Weight: 0.002 grams (approx.)
- Ordering Information, see Page 3



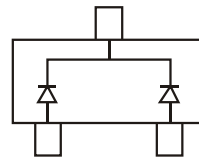
SOT-523			
Dim	Min	Max	Typ
A	0.15	0.30	0.22
B	0.75	0.85	0.80
C	1.45	1.75	1.60
D	—	—	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
J	0.00	0.10	0.05
K	0.60	0.80	0.75
L	0.10	0.30	0.22
M	0.10	0.20	0.12
N	0.45	0.65	0.50
α	0°	8°	—
All Dimensions in mm			



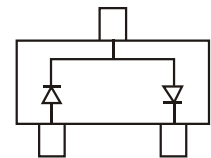
SDMP0340LT Marking: SM



SDMP0340LAT Marking: SQ



SDMP0340LCT Marking: SP



SDMP0340LST Marking: SN

Maximum Ratings @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	40	V
RMS Reverse Voltage	V _{R(RMS)}	28	V
Forward Continuous Current (Note 1)	I _{FM}	30	mA
Non-Repetitive Peak Forward Surge Current @ 8.3ms Single half sine-wave superimposed on rated load (JEDEC method)	I _{FSM}	200	mA
Power Dissipation (Note 1)	P _d	150	mW
Thermal Resistance, Junction to Ambient (Note 1)	R _{θJA}	833	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-40 to +125	°C

Electrical Characteristics @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	V _{(BR)R}	40	—	—	V	I _R = 10μA
Forward Voltage Drop (Note 2)	V _F	—	290	370	mV	I _F = 1mA
Leakage Current (Note 2)	I _R	—	—	1.0	μA	V _R = 10V
Total Capacitance	C _T	—	2	—	pF	V _R = 1V, f = 1.0 MHz

- Notes: 1. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
2. Short duration test pulse used to minimize self-heating effect.

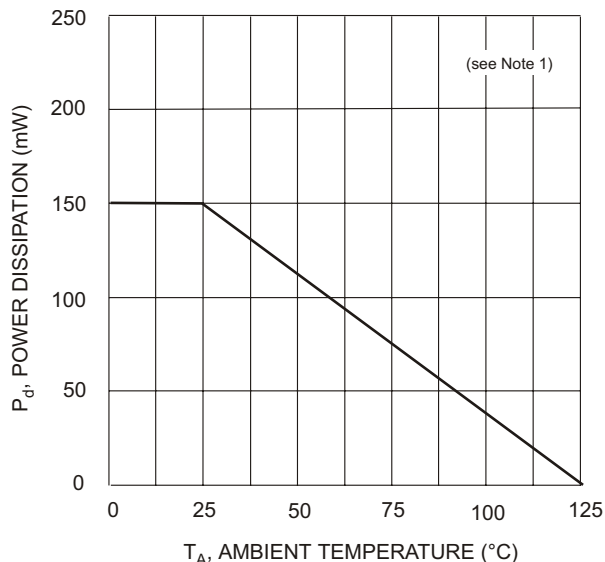


Fig. 1, Power Derating Curve

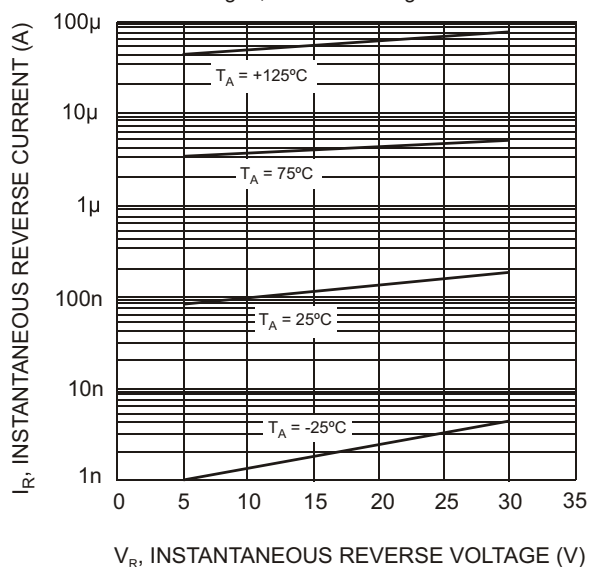


Fig. 3 Typical Reverse Characteristics

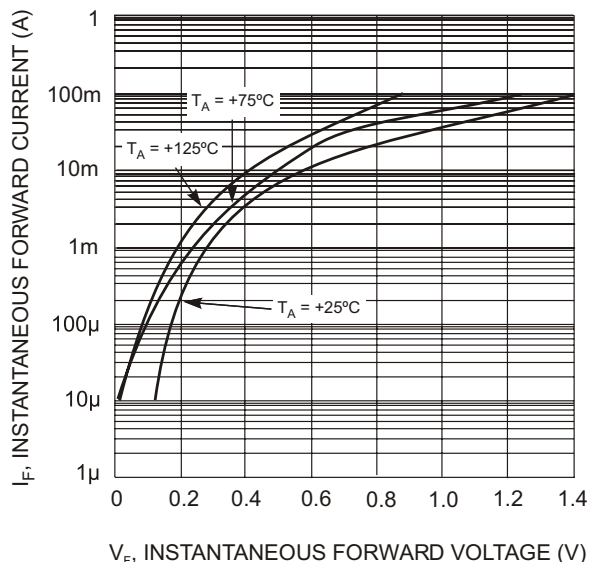


Fig. 2 Typical Forward Characteristics

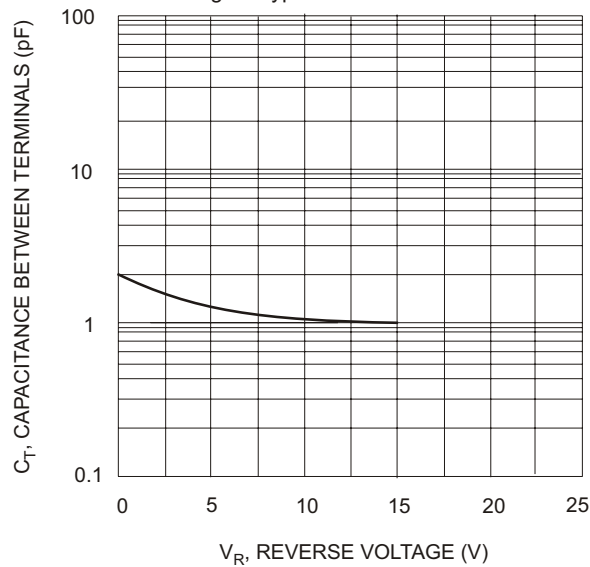


Fig. 4 Typical Capacitance Between Terminals Characteristics

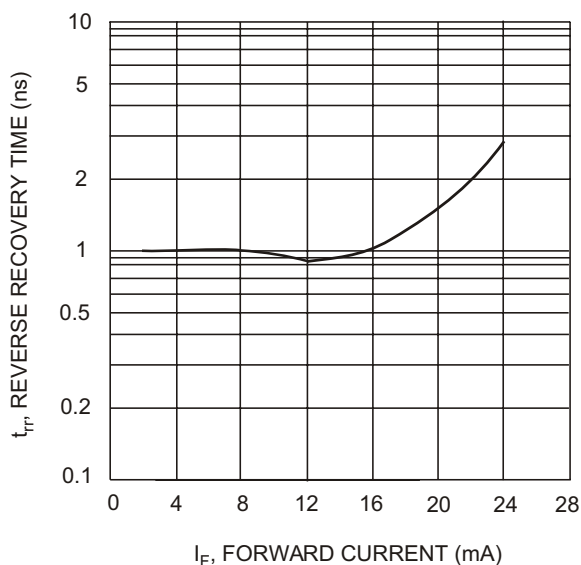
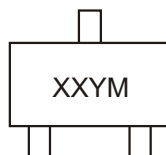


Fig. 5 Typical Reverse Recovery Time Characteristics

Ordering Information (Note 3)

Device	Packaging	Shipping
SDMP0340LT-7	SOT-523	3000/Tape & Reel
SDMP0340LST-7	SOT-523	3000/Tape & Reel
SDMP0340LCT-7	SOT-523	3000/Tape & Reel
SDMP0340LAT-7	SOT-523	3000/Tape & Reel

- Notes:
- For Packaging Details: go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.
 - For Lead Free version (with Lead Free terminal finish) part number, please add "-F" suffix to part number above.
Example: SDMP0340LAT-7-F.

Marking Information


XX = Product Type Marking Code (See Page 1)
 YM = Date Code Marking
 Y = Year (ex: N = 2002)
 M = Month (ex: 9 = September)

Date Code Key

Year	2001	2002	2003	2004	2005	2006	2007	2008	2009
Code	M	N	P	R	S	T	U	V	W

Month	Jan	Feb	March	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D